



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : LEE et al. Confirmation No: 4969
Appl. No. : 10/664,981
Filed : September 22, 2003
Title : SEMICONDUCTOR PACKAGE WITH THERMAL
ENHANCE FILM AND MANUFACTURING METHOD
THEREOF

TC/A.U. : 2815
Examiner : C.C. Chu

Docket No.: : LEEEC3073/REF
Customer No: : 23364

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of September 22, 2004, in connection with the above-identified application. The period for response to this Official Action has been extended to expire on January 22, 2005, by the filing herewith of a petition for a one month extension of time and payment of the required fee.

Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.